

WHAT IS CLAIMED IS:

1 1. An electronic component comprising:
2 a ceramic board containing glass; and
3 a conductor film stuck to the ceramic board,
4 wherein the conductor film is formed by firing a conductor paste
5 containing a silver particle having a specific surface area of 0.3 m²/g to 3.0 m²/g
6 at a temperature having a difference of ±50°C from a softening temperature of
7 the glass.

1 2. An electronic component comprising:
2 a ceramic board containing glass; and
3 a conductor film stuck to the ceramic board and containing silver,
4 wherein the glass intrudes into the conductor film from a surface on the
5 ceramic board side and is not exposed on a surface of the opposite side of the
6 ceramic board.

1 3. A method of manufacturing an electronic component which has a
2 conductor film formed on a glass ceramic board, comprising the steps of:
3 a process for sticking a conductor paste containing a silver particle
4 having a specific surface area of 0.3 m²/g to 3.0 m²/g and no glass onto a glass
5 ceramic sheet board which has not been sintered or has been sintered; and
6 a process for firing the conductor paste at a temperature having a
7 difference of ±50°C from a softening temperature of the glass and for forming
8 the conductor film on the glass ceramic board.